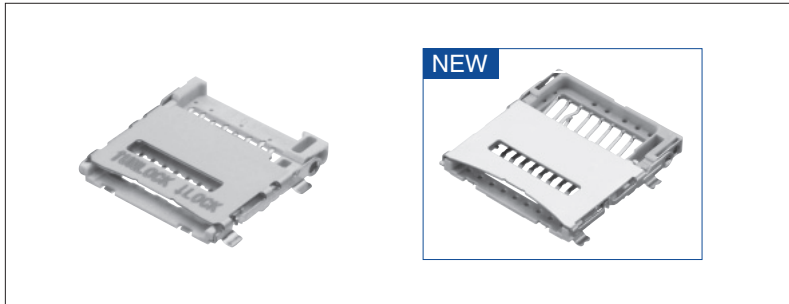


Connector for microSD™ Card (Hinge Cover Type)

SCHB Series



Hinge cover type with improved card retention.



Typical Specifications

Items		Specifications
Structure	Applicable media	microSD™ Card
	Mounting type	Surface mounting type
	Mounting style	Standard mount
	Media ejection structure	Manual insertion/removal
Performance	Operating temperature range	-20°C to +70°C
	Voltage proof	500V AC 1minute
	Insulation resistance (Initial)	1,000MΩ min.
	Contact resistance (Initial)	100mΩ max.
	Insertion and removal cycle	5,000cycles

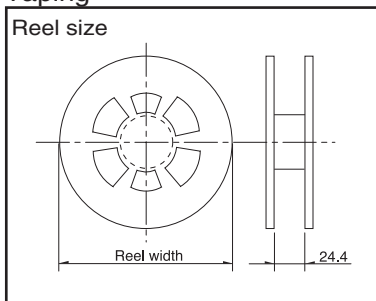
Product Line

Media ejection structure	Mounting system	Feature	Stand-off (mm)	Packing system	Product No.	Drawing No.
Manual insertion/removal	Standard mount	Without switch	0	Taping	SCHB1A0205	1
		With switch			SCHB1B0100	2

Packing Specifications

Taping

Unit:mm



Product No.	Number of packages (pcs.)			Reel width (mm)	Tape width (mm)	Export package measurements (mm)
	1 reel	1 case /Japan	1 case /export packing			
SCHB1A0205	1,400	4,200	8,400	330	24	353 × 353 × 249
SCHB1B0100	1,500	4,500	9,000	380		403 × 403 × 249



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ALPS

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For W-SIM

For Memory Stick Micro™

For Memory Stick™

Combine Type

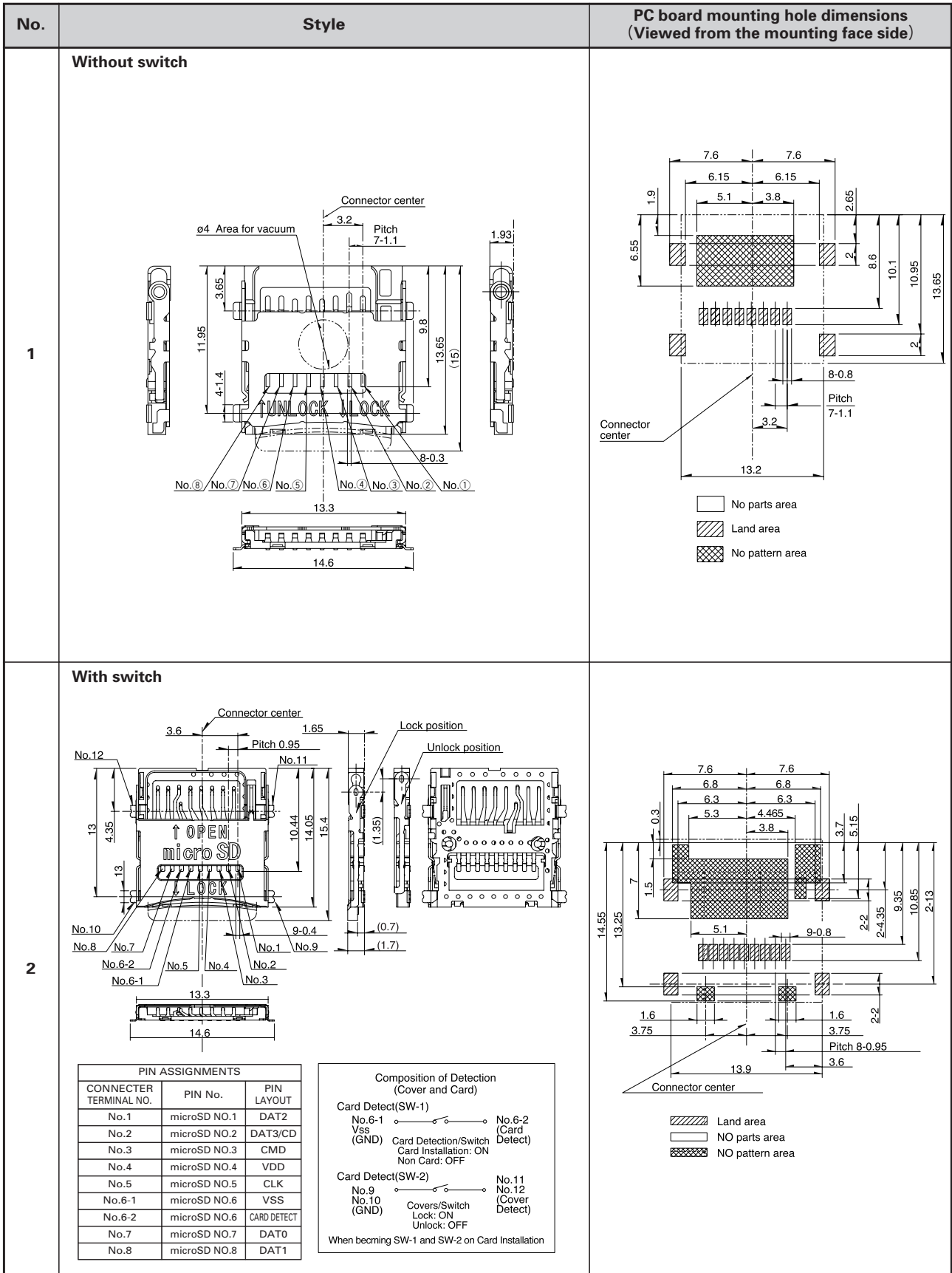
For Compact Flash™

For CMOS Camera Module

Dimensions

Unit:mm

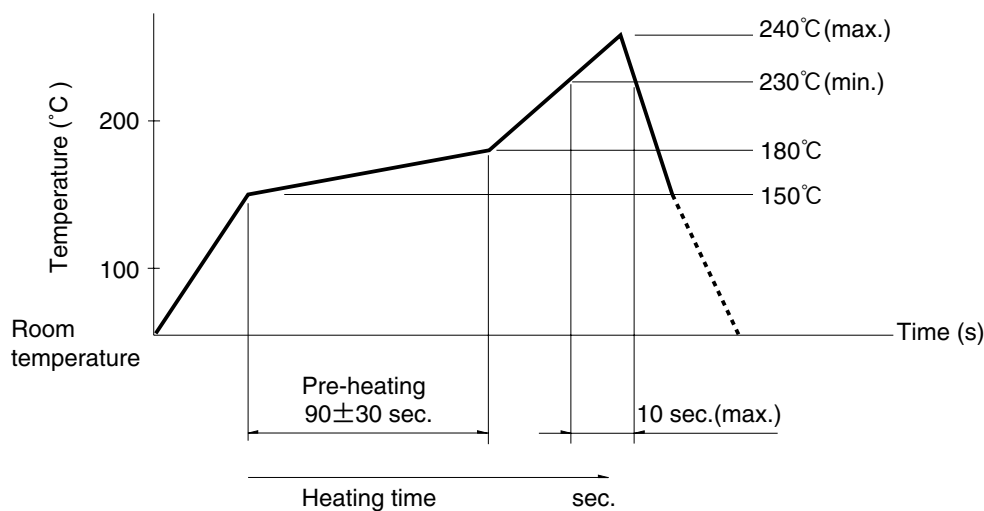
- For SD Memory Card
- For microSD™ Card
- For SIM Card 8pins
- For W-SIM
- For Memory Stick Micro™
- For Memory Stick™
- Combine Type
- For Compact Flash™
- For CMOS Camera Module



Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T).
3. Temperature profile (Surface of products).



Cautions for using this product

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. Avoid use of water-soluble soldering flux, since it may corrode the product.
3. Check and conform to reflow soldering requirements under actual mass production conditions.
4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
5. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For W-SIM

For Memory Stick Micro™

For Memory Stick™

Combine Type

For Compact Flash™

For CMOS Camera Module